

L Number	Hits	Search Text	DB	Time stamp
1	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 15:32
2	91	5426072.URPN.	USPAT	2004/04/01 15:32
3	7	("3602981" "3623219" "4022927" "4423435" "4980308" "5244817" "5279991").PN.	USPAT	2004/04/01 16:19
4	130	((((three adj dimensional) or "three-dimensional" or "3d") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:33
5	22	((three adj dimensional) or "three-dimensional" or "3d") same (soi or (silicon adj3 insulat\$3)) same (interconnect or vertical) and (@ad<19990423 or @rlad<19990423)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:46
6	2423	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:47
8	12	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)) and interconnect and 438/459.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:50
7	260	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)) and interconnect and 438/\$3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 17:00
-	0	soi and ((via hole open\$3 contact) with fox) and (thin\$4 with backside with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 15:32
-	124	soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:06
-	75	(soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:41
-	69	soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:54
-	41	(soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:00
-	36	(form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
-	25	((form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23

-	106	soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
-	45	(soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:04
-	2559	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
-	404	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:19
-	124	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:22
-	26	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:20
-	69	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	0	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-	13	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-	136	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	0	((vertical\$2 or vertigal) adj integratable) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	3	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-	0	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
-	25	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
-	3347	(438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
-	2559	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:42

-	42	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:42
-	24	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
-	134	soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:06
-	3	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and (soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
-	39	(form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
-	2	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
-	113	soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
-	10	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and (soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
-	73	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((thin\$3 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
-	28	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((thin\$3 or remov\$3) with substrate) and soi) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15